

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT4228031

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHENG-YI WU	09/28/2016
LI-HSUAN CHU	09/28/2016
CHING-WEN WEN	09/30/2016
CHIA-CHUN HUNG	09/28/2016
CHEN LIANG CHANG	09/28/2016
CHIN-SZU LEE	09/28/2016
HSIANG LIU	10/12/2016
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
Street Address:	NO. 8, LI-HSIN RD. 6
Internal Address:	SCIENCE-BASED INDUSTRIAL PARK
City:	HSIN-CHU
State/Country:	TAIWAN
Postal Code:	300-77
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15282258
CORRESPONDENCE DATA	
Fax Number:	(214)200-0853
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2146515000
Email:	ipdocketing@haynesboone.com
Correspondent Name:	HAYNES AND BOONE, LLP IP SECTION
Address Line 1:	2323 VICTORY AVENUE
Address Line 2:	SUITE 700
Address Line 4:	DALLAS, TEXAS 75219
ATTORNEY DOCKET NUMBER:	2016-0338/24061.3390US01
NAME OF SUBMITTER:	DELL WHITTON
SIGNATURE:	/Dell Whitton/

PATENT

DATE SIGNED:	01/17/2017
Total Attachments: 3 source=3390US01 - Assignment#page1.tif source=3390US01 - Assignment#page2.tif source=3390US01 - Assignment#page3.tif	

Docket No.: P20160338US00/24061.3390US01
Customer No.: 000042717

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|------------------|----|--|
| (1) | Cheng-Yi Wu | of | Taichung City, Taiwan, Republic of China |
| (2) | Li-Hsuan Chu | of | Taichung City, Taiwan, Republic of China |
| (3) | Ching-Wen Wen | of | Taichung City, Taiwan, Republic of China |
| (4) | Chia-Chun Hung | of | Taichung City, Taiwan, Republic of China |
| (5) | Chen Liang Chang | of | New Taipei City, Taiwan, Republic of China |
| (6) | Chin-Szu Lee | of | Taoyuan City, Taiwan, Republic of China |
| (7) | Hsiang Liu | of | Hsinchu, Taiwan, Republic of China |

have invented certain improvements in

AN IMPROVED DIELECTRIC FILM FOR FABRICATION

for which we have executed an application for Letters Patent of the United States of America,

 of even date filed herewith; and
 X filed on 09-30-2016 and assigned application number 15/282,258; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

Docket No.: P20160338US00/24061.3390US01

Customer No.: 000042717

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Cheng-Yi Wu

Residence Address: No. 36-37, Junfu 13th Road, Beitun District
Taichung City 406, Taiwan, Republic of China

Dated: 2016 09 28

Cheng-yi Wu
Inventor Signature

Inventor Name: Li-Hsuan Chu

Residence Address: 18F.-1, No. 482, Yumen Road, Xitun District,
Taichung City 407, Taiwan, Republic of China

Dated: 2016 09 28

LI-HSUAN CHU
Inventor Signature

Inventor Name: Ching-Wen Wen

Residence Address: No. 18, Lane 39, Liwen Street, Taiping District
Taichung City 411, Taiwan, Republic of China

Dated: 2016 09 30

Ching-Wen Wen
Inventor Signature

Docket No.: P20160338US00/24061.3390US01

Customer No.: 000042717

Inventor Name: Chia-Chun Hung

Residence Address: No. 31, Renyou Lane, Beitun District
Taichung City 406, Taiwan, Republic of China

Dated: 9/28, 2016

Chia-Chun Hung
Inventor Signature

Inventor Name: Chen Liang Chang

Residence Address: 5F., No. 30, Zhongxiao 3rd Road, Linkou District
New Taipei City 244, Taiwan, Republic of China

Dated: 9/28, 2016

Chen Liang Chang
Inventor Signature

Inventor Name: Chin-Szu Lee

Residence Address: No. 10, Sub-alley 21, Alley. 14, Lane 131, Section 2, Fudan Road
Pingzhen District, Taoyuan City 32449, Taiwan, Republic of China

Dated: 9/28, 2016

Chin-Szu Lee
Inventor Signature

Inventor Name: Hsiang Liu

Residence Address: 103, Zefan Rd. Hsinchu 30067, Taiwan, Republic of China

Dated: 10/12/2016

Hsiang Liu
Inventor Signature